



CUSTOMER ADVISORY ADV0406

TQFP 32 PACKAGE TOP MOLD AND EJECTOR SIZE CHANGE

Change Description:

Due to assembly process improvements undertaken at our assembly supplier, slight dimensional changes are being made to the 32 lead thin quad flat pack (TQFP) packages. The dimension changes involve an increase of the top mold size dimension from 6.9 mm to 7.0 mm and the top mold ejector size from 0.8 mm to 1.2 mm. With this change, both the top and bottom mold dimensions will be 7.0 mm. This change does not affect the function or reliability of the products.

This change will not affect the package thickness or overall package outline dimensions. The moisture rating is unchanged and the package continues to conform to the JEDEC outline specification (MS-026).

Figure 1 illustrates the current and new packages and the changes implemented.



Figure 1 – Current and New TQFP 32 Package Dimensions

Reason for Change:

The molded outline change of this package offers better moldability and provides improvements in productivity, cycle time, and yield performance in manufacturing.

Products Affected:

This change affects Altera® devices in the TQFP 32 package assembled by Amkor Korea.

Product Traceability and Transition Dates:

This change will be implemented beginning June 2004. The new TQFP 32 package is clearly visible from the larger ejector for packages marked with “Korea” as the country of origin.

Contact:

For more information on this advisory, please contact your local Altera sales representative or the Altera Customer Quality Engineering Department.